

Congress of the United States
Washington, DC 20515

June 11, 2024

The Honorable Gina Raimondo
Secretary
U.S. Department of Commerce
1401 Constitution Ave, NW
Washington, DC 20230

Dear Secretary Raimondo,

As members of the Indiana congressional delegation, we are writing to offer our strong support for the application submitted by SK hynix for funding through the U.S. Department of Commerce's CHIPS Incentives Program Notice of Funding Opportunity for Commercial Fabrication Facilities.

SK hynix's announced \$3.87 billion investment will establish a state-of-the-art advanced packaging facility in the Purdue Research Park in West Lafayette, Indiana. Once mass production begins in 2028, the facility will bring to the United States industry-leading wafer-level packaging processes for high-bandwidth memory (HBM), a crucial component of further artificial intelligence (AI) innovation, as well as an advanced packaging R&D facility.

As the leading HBM memory provider, SK hynix will play a vital role in stabilizing the semiconductor supply chain by securing a production site for chips for AI applications, strengthening national security through the mass production of HBM chips in the U.S., and constructing an advanced packaging R&D facility, which we see as a key priority of the CHIPS Incentives Program.

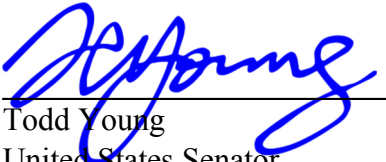
HBM chips are the optimal memory devices to work in concert with leading-edge logic chips (e.g., graphics processing units, or GPUs) to train large language models for AI applications. This investment establishes a core component of the AI value chain in the U.S. and will be pivotal to ensuring a domestic supply of the very chips needed to continue to assert U.S. leadership in AI.

To bolster U.S. leadership in innovation, SK hynix will collaborate closely with Purdue University and engage in collaborative research and development as the facility comes online. Specifically, R&D collaboration will focus on Advanced System Integration and Packaging to develop new heterogeneous packaging solutions, utilizing the Birck Nanotechnology Center's labs and SK hynix's R&D pilot line to build and test new packaging systems.


SK hynix's project, which will create up to 1,000 jobs by 2030, represents a significant step toward the continued development of a Silicon Heartland in the Midwest. Through SK hynix's partnerships with Purdue University and Ivy Tech Community College, Indiana will further grow a robust talent pipeline as training programs and curricula are developed to enable students to attain the skills needed for semiconductor manufacturing.

SK hynix's investment will help the U.S. to reestablish its leadership in semiconductor technology and represents a significant step in developing a robust, U.S.-based semiconductor ecosystem. We offer our support and ask that you give the application full and fair consideration within applicable laws and regulations.

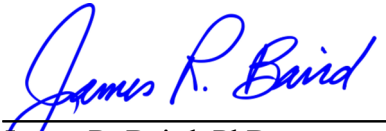
Sincerely,



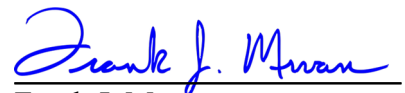
Todd Young
United States Senator



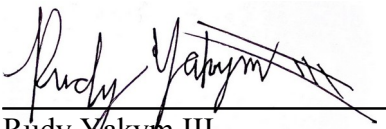
Mike Braun
United States Senator



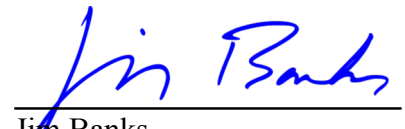
James R. Baird, PhD
Member of Congress




Frank J. Mrvan
Member of Congress




Rudy Yakym III
Member of Congress



Jim Banks
Member of Congress



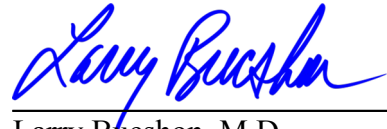
Victoria Spartz
Member of Congress



Greg Pence
Member of Congress



André Carson
Member of Congress



Larry Bucshon, M.D.
Member of Congress



Erin Houchin
Member of Congress